DLP® LightCrafter™ Evaluation Module (EVM)

User's Guide



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Contents

Prefa	ace		4
1	DLP®	LightCrafter™ Module Overview	5
	1.1	Welcome	5
	1.2	What is in this Module?	. 5
		1.2.1 Light Engine	. 6
		1.2.2 LED Currents	. 7
		1.2.3 Driver Board	. 7
		1.2.4 System Board	. 9
	1.3	Other items needed for operation	10
	1.4	DLP® LightCrafter™'s Connections	11
	1.5	DLP® LightCrafter™'s Dimensions	12
2	Softw	are Overview	14
	2.1	DLP® LightCrafter™ Software	14
	2.2	Embedded Linux Kernel	14
	2.3	First Time Connection to a Windows PC	15
	2.4	First Time Connection to a Windows 7 PC	15
	2.5	PC Software	18
		2.5.1 LED Current Settings	19
		2.5.2 Static Image Mode	20
		2.5.3 Internal Test Pattern	20
		2.5.4 HDMI Video	21
		2.5.5 Pattern Sequence	21
	2.6	Firmware Upgrades	23
	2.7	Solutions	24
3	Patter	n Sequences	25
	3.1	Pattern Sequence Background	25
	3.2	External Patterns	26
	3.3	Internal Patterns	27
4	Conne	ectors	29
	4.1	Trigger Connector	29
	4.2	Camera Connector	29
	4.3	UART	30
	4.4	I ² C	30
	4.5	Fan	30
	4.6	Power	31
Revi	sion A I	History	32
Revi	sion B I	listory	32

2



List of Figures

1.	DLP® LightCrafter™ Evaluation Module	4
1-1.	DLP® LightCrafter™ Block Diagram	6
1-2.	0.3" DMD Pixel Geometry	6
1-3.	DLP® LightCrafter™ Driver Board Block Diagram	8
1-4.	DLP® LightCrafter™ System Board Block Diagram	9
1-5.	DLP® LightCrafter™ Connector Locations	12
1-6.	DLP® LightCrafter™ Module Dimensions	13
2-1.	DVSDK Software Platform	14
2-2.	DLP® LightCrafter™ GUI	18
2-3.	DLP® LightCrafter™ GUI Functionality	19
2-4.	GUI - Static Image Mode	20
2-5.	GUI - Internal Test Pattern	21
2-6.	Trigger Period	22
2-7.	Pattern Sequence	22
2-8.	Firmware Upgrades	23
2-9.	Solutions	24
3-1.	The Relationship between Bit Planes and 24-bit RGB Images	25
3-2.	Bit Partition	25
3-3.	Bit Planes and Triggers	26

List of Tables

1-1.	DLP® LightCrafter™Light Engine Specifications	7
2-1.	LED Current Settings	20
3-1.	Allowable External Pattern Combinations	27
3-2.	Maximum Internal Pattern Rate	27
3-3.	Internal Pattern Exposure Time	28
4-1.	Trigger Connector Pins	29
4-2.	Camera Connector Pins	29
4-3.	UART Connector Pins	30
4-4.	I ² C Connector Pins	30
4-5.	Fan Connector Pins	31
4-6.	Power Connector Pins	31

3



DLPU006B–January 2012–Revised July 2013

Read This First

About This Guide

The DLP® LightCrafter[™] is a third party implementation of a next generation DLP Pico reference design to enable faster development cycles for applications requiring small form factor, and intelligent pattern display.

This guide is an introductory document for the DLP® LightCrafter[™] that provides an overview of the system and its software. Other documents provide more in-depth information of the hardware and software features of DLP® LightCrafter[™]'s components.



Figure 1. DLP® LightCrafter™ Evaluation Module

Related Documentation From Texas Instruments

DLPC300 Data Sheet: *DLP Digital Controller for DLP3000 DMD*, TI literature number <u>DLPS023</u> DLP3000 Data Sheet: *DLP 0.3 WVGA DDR Series 220 DMD*, TI literature number <u>DLPS022</u> *DLPC300 Software Programmer's Guide*, TI literature number <u>DLPS023</u> DLP® LightCrafter[™] DM365 Command Interface Guide, TI literature number DLPU007

If You Need Assistance

Refer to the DLP and MEMS TI E2E Community support forums.

DLP is a registered trademark of Texas Instruments.



DLP® LightCrafter™ Module Overview

This chapter introduces the DLP® LightCrafter[™] module.

1.1 Welcome

Your new DLP® LightCrafter™ module will allow you to evaluate TI's DLP Pico platform along with TI's DaVinci Technology and the DM365 architecture.

This technology brings together a set of components providing an efficient and compelling system solution for:

- Small display projector: Embedded display, Interactive display, Information overlay
- Structured light applications: 3D modeling/design, Biometric: fingerprint identification and face recognition, Machine vision and inspection
- Medical and life sciences: Vascular imaging, Dental impression scanner, Intraoral dental scanners, Orthopaedics, Prosthesis, CT/MRI/X-ray marking, Retail cosmetics

1.2 What is in this Module?

The DLP® LightCrafter[™] module consists of three subsystems:

- Light engine includes the optics, red, green, and blue LEDs, and the 608 x 684 diamond pixel 0.3" WVGA DMD. Capable of 20 lumens out-of-the-box with support to 50 lumens with user's addition of active cooling.
- Driver board includes the LED driver circuits, DLPC300 DMD Controller, power management circuits and MSP430.
- System board includes TMS320DM365, FPGA, and several connectors for external inputs.

Figure 1-1 shows the major hardware components.

5





Figure 1-1. DLP® LightCrafter™ Block Diagram

1.2.1 Light Engine

Young Optics, Inc. developed the DLP® LightCrafter[™]'s light engine. The light engine includes the DLP3000 0.3" DMD with 415,872 mirrors arranged in a 608 by 684 with the diamond pattern geometry shown in Figure 1-2



Figure 1-2. 0.3" DMD Pixel Geometry

The DMD is vertically mounted at the end of the light engine. The light engine, including the LEDs and not including the heat sinks, has a length of 39.3 mm, width of 41.6 mm, and height of 11 mm. Table 1-1 lists the specifications of the light engine:

6



	MIN	тур	MAV	LINIT
	MIIN	ITP	IVIAA	UNIT
	10	@ 0.6W LED		
Brightness	25	@ 1.85W LED		Im
	30	@ 2.25W LED		
Brightness uniformity (JBMA)		70		%
ANSI contrast		43:1		
Full-on full-off contrast		685:1		
Color uniformity (CIE x)		0.03		
Color Uniformity (CIE y)		0.04		
Throw ratio		1.66		
Offset		100		%
Focus range	364		2169	mm
Image diagonal size	10		60	inch
Focus stroke		1		mm

Table 1-1. DLP® LightCrafter™Light Engine Specifications

1.2.2 LED Currents

DLP® LightCrafter[™] passively cooled systems (no extra heat sinks or fans) have a thermal limit resulting in LED currents under 633 mA.

DLP® LightCrafter[™] actively cooled systems (extra heat sink and fan) have a thermal limit resulting in LED currents under 1.5 A.

To be used as part of an overall thermal management system, the current software has a safety shutdown if excessive heat is measured at the DMD.

1.2.3 Driver Board

Figure 1-3 shows the DLP® LightCrafter™'s driver board block diagram.





Figure 1-3. DLP® LightCrafter™ Driver Board Block Diagram

The major components of the DLP® LightCrafter™'s driver board are:

- DLP3000 0.3" DMD
- DLPC300: DLP3000 controller with
 - 2MB SPI FLASH that contains DLPC300 firmware
 - 32MB mDDR that buffers images for the DLP3000
- MSP430:
 - Controls power supply sequencing and system initialization
 - LED driver control
 - Shutdown system upon detection of low input voltage
 - Measure thermistors and shutdown system when maximum temperature ratings are exceeded.
- LED driver circuitry
- Power management:
 - TPS63020: Buck/Boost Regulator for LED supplies
 - TPS63020: Buck/Boost Regulator for 3.3 V supply
 - TPS62260: Step Down Converter for DLPC300 2.5 V supply
 - TPS62400: Step Down Converter for DLPC300 1.0 V and 1.8 V supply
 - TPS65120: 4-CH Bias for DMD VRST and VBIAS supplies
 - TPS71501: LDO for DMD VOFS supply



1.2.4 System Board

Figure 1-4 shows the DLP® LightCrafter™'s system board.



Figure 1-4. DLP® LightCrafter™ System Board Block Diagram

The major components of the system board are:

- Altera Cyclone IV FPGA:
 - Controls video muxing (external miniHDMI or DM365)
 - Controls LEDs enables
 - Generates programmable camera triggers
 - Manages four internal buffers for fast pattern display
- DM365: Embedded Linux main processor that controls camera interface, connectivity with PC, non-volatile storage (Micro-SD and NAND Flash), FPGA control, video output, and video buffer in DDR2.
 - 64MB DDR2 memory
 - Micro-SD connector
 - Mini-USB connector
 - UART mini-plug
- miniHDMI connector
- Power management:
 - TPS650531: 2-Step Down Converter for FPGA's and DM365's 1.2 V and 1.8 V supplies with three LDOs for FPGA's 2.5V supply and camera interface optional 2.8 V supply



1.3 Other items needed for operation

The DLP® LightCrafter[™] module is a flexible, ready to use evaluation module (EVM). However, DLP® LightCrafter[™] EVM does not ship with any cables, power supply, or additional hardware components. To use the EVM, you will need:

- Power supply: center positive 5-V output with 2- to 3-A current rating and a plug of 0.7 mm inner diameter x 2.35 mm outer diameter and 9.5-mm female shaft.
- Mini USB cable
- RS232 cable with 2.5-mm stereo plug

1.4 DLP® LightCrafter™'s Connections

DLP® LightCrafter[™] offers the following connectivity options:

- Power Connector: supplies 5-V to DLP® LightCrafter™ module.
- Output: 5-V with 2- to 3-A current rating
- Inner Plug diameter: 0.7-mm
- Outer diameter: 2.35-mm
- Female shaft length: 9.5-mm
- Positive center
- Mini-HDMI: supports external video input with 608 x 684 resolution at 60 Hz.
- Micro-SD: tested to support up to 4GB, class 10, high capacity cards for DM365 software and local data storage.
- Mini USB: interfaces to PC as a slave device. A program running on the PC will issue commands to the DLP® LightCrafter[™] module.
- Camera Connector: 28-pin connector using ITU-R BT.656 compatible camera interface. The camera interface supports up to 12-bit data.
- Trigger connector: supports external or internally generated triggers for camera capture.
- Serial FLASH programming connectors:
 - Driver board: programs the MSP430 FLASH and the DLPC300 serial FLASH.
 - System board: programs the FPGA serial FLASH.
- UART mini-plug: allows serial messages with the following RS-232 compatable serial configuration:
 - 2.5-mm stereo plug: tip-RX, ring-TX, ground-GND
 - Bits per second: 115200
 - Data Bits: 8
 - Parity: None
 - Stops Bits: 1
 - Flow Control: None

Figure 1-5 depicts the connectors and their respective locations.





- 1. Trigger Input/Output
- 2. Mini USB
- 3. Power Connector
- 4. Mini HDMI
- 5. UART
- 6. Power Socket
- 7. l²C
- 8. FPGA SPI Flash Programming Interface
- 9. MSP430/DLPC300 Flash Programming Interface
- 10. On/Off Button Do not turn off while the Linux system is booting
- 11. Input Selection Button (DM365/Internal Test Pattern/HDMI input)
- 12. Ethernet PHY
- 13. Fan
- 14. Camera
- 15. Focus Control
- 16. Boot Mode Selection Switch
- 17. Micro-SD card

Figure 1-5. DLP® LightCrafter™ Connector Locations

1.5 DLP® LightCrafter™'s Dimensions

The DLP® LightCrafter[™] optical engine is mounted on top of a thermal plate to provide passive cooling to the module. The DLP3000, 0.3" DMD, is vertically mounted at the end of the optical engine and attached with a connector to the Driver Board. The System Board is mounted on top of the Driver Board. This module has dimensions of 116.5 mm long, 65 mm wide, and 23 mm tall. Figure 1-6 illustrates DLP® LightCrafter[™] dimensions.











Software Overview

This chapter introduces the PC software provided with the DLP® LightCrafter[™] Module.

2.1 DLP® LightCrafter[™] Software

The DLP® LightCrafter[™] module software is based on TI's DVSDK platform. The DVSDK platform is a collection of royalty free software components built upon Linux operating system and pre-tested by TI. The software components include Linux kernel, Linux filesystem, Linux product support package (PSP), application framework (APIs), codec libraries (MPEG4, H.264, MPEG2, G.711, JPEG), example programs, DSP Codegen, and CodeSourcery tool chain with IDE for cross-compiling and debugging target systems.



Figure 2-1. DVSDK Software Platform

2.2 Embedded Linux Kernel

Out of the box, the DLP® LightCrafter[™] boots from the on-board NAND FLASH. The DM365 acts as the main processor of the system and boots as an embedded Linux device. The Linux filesystem resides on the micro-SD card. Thus, the DLP® LightCrafter[™] does not require an NFS mount nor a TFTP server to run. The embedded Linux system utilizes Remote Network Drivers Interface Specification (RNDIS) to send packets through USB. Currently, DLP® LightCrafter[™] has a fixed IP address of 192.168.1.100.

DLP® LightCrafter[™]'s UART port serves as a console output of the embedded Linux device. The DM365 will send error messages through the UART and accept root level commands. A 2.5 mm stereo plug to female DB9 connector as shown below is needed to connect the DLP® LightCrafter[™]'s UART port to a PC. For PCs with only USB ports, a USB to RS232 adapter with FTDI chipset is recommended.

To view UART console messages, configure a terminal emulator with the following parameters:

- Baud: 115,200
- Data Bits: 8
- Stop Bits: 1
- Parity: None
- Flow Control: None



First Time Connection to a Windows PC

2.3 First Time Connection to a Windows PC

The first time the cable is connected on Windows XP systems a pop-up window appears stating that a new hardware device called a "RNDIS/Ethernet Gadget" was found. Then follow these steps:

1. This should bring up the "Found New Hardware" dialog, select "Install the software automatically (Recommended)." Click on Next. Windows XP Service Pack 2 or greater includes the RNDIS drivers, so these drivers should be found by the OS.



2. Verify "USB Ethernet/RNDIS Gadget" is detected by the hardware wizard.

Found New Hardware Wi	ard	Found New Hardware Wizard	
	Welcome to the Found New Hardware Wizard Windows will search for current and updated software by looking on your computer, on the hardware installation (D), or on the Windows Update Web and (with your permission). Read our participation		is wizard helps you install software for: RNDIS/Ethernet Gadget
	Can Windows connect to Windows Update to search for software? Image: this time only Yes, now and gively time I connect a device No, not this time Click. Next to continue.		If your hardware came with an installation CD or floppy disk, insert it now. at do you want the wizard to do? (Install free software automatically (Recommended) Install from a list or specific location (Advanced) k Next to continue.
	< Back Next> Cancel		< Back Next > Cancel
	Hardware Update Wizard		
	Please wait while the wizard searches.		
	USB Elternet/RNDIS Godget #	2	
		Q	
		KBack Next> Cancel	

2.4 First Time Connection to a Windows 7 PC

The first time the cable is connected on Windows 7 systems a pop-up window appears stating that a new hardware device called a "RNDIS/Ethernet Gadget" was found. Then follow these steps:

1. This should bring up the "Driver Software Installation" dialog. Windows 7 will try to automatically download the driver and fail. A message indicating that the "device driver software was not successfully installed is displayed."

evice driver software was	not successfully installed
Please consult with your device mar	ufacturer for assistance getting this device installed.
RNDIS/Ethernet Gadget	🔀 No driver found
What can I do if my device did not in	stall properly?

- 2. Right click on "My Computer," choose manage and open the Device Manager.
- 3. Expand Other Devices and right click on "RNDIS Kit."
- 4. Select "Update Driver Software."



🚔 Device Manager		_ X
File Action View	Help	
♦ ♦ □ □	🛛 📰 🙉 😭 🍋 🛤	
	C51B	
Batteries		
🦻 👎 Computer		
🛛 👝 Disk drives		
🔉 📲 Display ada	pters	
DVD/CD-R	OM drives	
Floppy disl	drives	
Floppy driv	e controllers	
Human Int	ertace Devices	
DE ATA/A	nices	
Keyboards	vices	
Mice and o	ther pointing devices	
Monitors		
🦻 💇 Network a	lapters	
a 🧓 Other devi	tes	
RND	Update Driver Software	
Process	Disable	
Sound,		
System	Uninstall	
Driversa	Scan for wardware changes	
	Properties	
ican for changed or ne	w Plug and Play devices.	

5. On the "Update Driver Software" dialog, select "Browse my computer for driver software."

+	Search automatically for updated driver software Windows will search your computer and the Internet for the latest driver software for your device, unless you've disabled this feature in your device installation settings.
•	Browse my computer for driver software Locate and install driver software manually.

- 6. On the next dialog, select "Let me pick from a list of device drivers on my computer."
- 7. Select Network Adapter.



elect your device's type from the list below.	
ommon <u>h</u> ardware types:	
Memory technology driver	*
🖄 Mice and other pointing devices	
A Microsoft Common Controller For Windows Class	
Mobile devices	
Modems	
Monitors	
Multifunction adapters	E
👚 Multi-port serial adapters	
💀 Network adapters.	
🛃 Network Client	
- Network Protocol	
BNetwork Service	-

8. Select Microsoft Corporation as the manufacturer. For network adapter, select "Remote NDIS Compatible Device."

electricition k Adapter		
Click the Network Ac	lapter that matche	s your hardware, then click OK. If you have an
installation disk for t	his feature, click Ha	we Disk.
Manufacturer	^ Network	Adapter:
Marvell	Remo	te NDIS based Internet Sharing Device
Microsoft	Remo	te NDIS Compatible Device
Microsoft Corporation	-	
and the second se		
Motorola Inc.		
Motorola Inc.	r	Have Di

9. After clicking on "Next," a dialog confirming that the driver software was installed successfully will be displayed.





2.5 PC Software

DLP LightCrafter includes a QT-based Graphical User Interface (GUI) to control the module through USB. QT is a Nokia cross-platform application and user interface framework with open source and commercial licenses. To install the QT GUI, follow these steps.

- 1. Download the most recent version of the DLP LightCrafter Software Bundle from http://www.ti.com/tool/dlplightcrafter
- 2. Extract the files from the downloaded zip file
- 3. Run the DLP LightCrafter Software Bundle installer
- 4. From the GUI directory of the installed software, double click on the LightCrafterGUI.exe to run the GUI
 - For example, on a Windows 7 computer the GUI would be installed in C:\Program Files (x86)\DLPLightCrafterSoftwareBundle-2.0.1\GUI\

			Display Mode			
	Connect		Static Image		~	Get
rsion			LED Current			
UI: Model	0.0.3	Get Versions	Red	Greer	n Blue	Set
PGA:	XXX.XXX					Get
DMI Video	Pattern Sequence	Test Pattern / Image	Camera / Trig	ger	Debug	
Video Settin	9		- Image Setti	ng		
Resolution	X		🗖 Lo	ong A>	cis Flip	Get
	Start Width	Get	🔲 SI	nort A	xis Flip	Set
Active Pix	0 0	Set	R	otate	-90 Degree	
Activo Lino	Start Heigh					
Hours and	U					
Video Mode	Setting					
Bit Depth	Frame Rate					
1	60					
	Set	Get				



The GUI has four main sections:

- 1. USB Connection: upper left portion of the window
- 2. Display Mode: upper right portion of the window
- 3. Display Mode Parameters: lower half of the window
- 4. Command Results: status bar at the bottom of the window

Clicking on a "Get" button will read the current settings of the module. Clicking on "Set" button will program the settings in the respective fields, of the Window, to the module.

After powering on the module wait for the splash screen to disappear, then connect the USB cable to the PC. Now, run the DLP® LightCrafter[™] GUI. The first action is to connect the module by clicking on the Connect button. At the bottom of the window, you will see the message "Connection Open."

		1	Display Mod	e			
	Disconnect		(charles to a	20	100	Get	
]	Static Imag	e		Set	
ersion			LED Current			£1	
UI:	0.0.3		Ped	Green	Blue	Set	ו
M365:	XXX.XXX	Get Versions	Ked	Green	Dide	Cat	1
PGA:	XXX.XXX					Gec	
IDMI Video	Pattern Sequence	Test Pattern / Image	Camera / T	rigger	Debug		
Static Image			/Internal 1	est Patter	n		
-		1				Get	
			Fine Che	cker Board	i 💊		=
	Browse	Load				Set	
Static Color							
Pred	Curre Dhue						
Reu	Green blue	Set					
-	l l	<u> </u>					

Figure 2-3. DLP® LightCrafter™ GUI Functionality

The GUI allows the following functionality:

- 1. Display a bitmap image by setting **Display Mode** to Static Image
- 2. Display DLPC300 test patterns by setting Display Mode to Internal Test Pattern
- 3. Display HDMI video input by setting **Display Mode** to HDMI Video
- 4. Display a pattern sequence by setting Display Mode to Pattern Sequence

2.5.1 LED Current Settings

The LED current is computed as follows:

LED Current (mA) = 1.8 * (LED Current Value) + 140

(1)

When at room temperature the maximum value allowed is dependent on the DLP® LightCrafter[™] cooling system. DLP® LightCrafter[™] passively cooled systems (no extra heat sinks or fans) have a thermal limit resulting in LED currents under 633 mA. DLP® LightCrafter[™] actively cooled systems (extra heat sink and fan) have a thermal limit resulting in LED currents under 1.5 A. Table 2-1 summarizes these constraints.

DLP® LightCrafter™	LED CUR	RENT VALUE	LED CURRENT	
COOLING SYSTEM	MINIMUM	MAXIMUM	MAXIMUM	
Passively cooled	0	274	633 mA	
Actively cooled	0	758	1.5 A	

Table 2-1. LED Current Settings

2.5.2 Static Image Mode

To upload a 608x684 pixel 24-bit RGB Windows bit-mapped image (*.BMP), follow these steps and refer to Figure 2-4:

- 1. Set Display Mode on upper left portion of the window to "Static Image" and click on "Set."
- 2. Select "Test Pattern/Image" tab on the lower half of the window.
- 3. Click on the "Browse" button to navigate the folders and select the bit-mapped file (*.BMP).
- 4. You also display a solid color screen by setting the LED current under the Static Color portion of the bottom of the display. The LED values allowed lie between 0 and 274, with 274 corresponding the highest current setting (633 mA).
 - NOTE: Static images must be in 608x684, 24-bit RGB, *.bmp format.

			Display Mo	de			Image Setting
	Disconnect		Static Ir	nage	~	Get	Long Axis Flip
Version						Set	Short Axis Flip
GUI:	0.3.6		LED Curren	x			Rotate -90 Degree
DM365:	2.3	Get Versions	Red	Green	Blue	Get	
FPGA:	2.3.34		274	274	274	Set	Set Get
MSP430:	2.3						
HDMI Video	Pattern Sequence	Test Pattern / Image	Solution /	Upgrade	Camera		
Static Image			Internal	Test Patter	n		
:/LightCraft	er/DM365/test/images	s/static/Garrita.bmp				Get	
	Provuso	Lord	Fine Ch	ecker Boari	H 🖌	Seet.	
	browse	LUGU					
Static Color							
Red	Green Phys						
Red	Green blue	Set					
		· · · · · · ·					

Figure 2-4. GUI - Static Image Mode

2.5.3 Internal Test Pattern

To display DLPC300 internal test patterns, follow these steps and refer to Figure 2-5:

- 1. Set Display Mode on upper left portion of the window to "Internal Test Pattern" and click on "Set."
- 2. Select "Test Pattern/Image" tab on the lower half of the window.
- 3. Pull down the menu under "Internal Test Pattern" and select the desired option. The options are:
 - Fine Checker Board
 - Solid Black
 - Solid White
 - Solid Blue
 - Solid Red



- Vertical Lines
- Horizontal Lines
- Vertical Lines (Fine)
- Horizontal Lines (Fine)
- Diagonal Lines
- Vertical Gray Ramp
- Horizontal Gray Ramp
- ANSI 4x4 Checker Board
- 4. Click on the "Set" button to display the selected pattern.
- 5. You can set the LED current values by writing a value between 0 and 274, with 274 corresponding the highest current setting (633mA) and clicking on "Set."

Discrimed: Get □ cong Axis Fip arsion Set Set W1: 0.3.6 ED Current: M955: 2.3 Get Versions FGA: 2.3.34 Get 1274 224 224 5x1c Image Solution / Upgrade Image: Load				Display Mode			Image Setting
ersion UI: 0.3.6 UI: Constrained of the set UI: 0.3.6 UI: 0.3.6 UED Current Red Green Blue Get Static Image S	Disconnect		Internal Test Patte	m v	Get	Long Axis Flip	
Uii: 0.3.6 MSS: 2.3 GR4: 2.3.34 SR4303: 2.3 MMU Vdeo Pattern Sequence Test Pattern / Image Salic Color Red Green Blue Satic Color	ersion					Set	Short Axis Flip
PGA: 2.3.34 274 274 Set Get SP430: 2.3 224 274 Set Get MUI Video Pattern Sequence Test Pattern / Image Indennal Test Pattern Static Image Indennal Test Pattern Get Browse Load Fine Checker Board Set Red Green Bue Set	₩365:	2.3	Get Versions	Red Green	Blue	Get	Rotate -90 Degree
KMI Video Pattern Sequence Test Pattern / Image Solution / Upgrade Camera Static Image Internal Test Pattern Get Browse Load Fine Checker Board Set	PGA: 15P430:	2.3.34 2.3		274 274	274	Set	Set Get
Static Load Static Color Red Green Blue Set	IDMI Video	Pattern Sequence	Test Pattern / Image	Solution / Upgrade	Camera		
Browse Load Static color Red Green Blue Set	Static Imag	9		Internal Test Patte	m		
Set	Static Color Red	Browse Green Blue	Load	Fine Checker Boar	d 💌	Set	
			Set				

Figure 2-5. GUI - Internal Test Pattern

2.5.4 HDMI Video

To display the HDMI video input, follow these steps:

- 1. Connect an active HDMI source to the mini HDMI connector showing in Figure 1-5.
- 2. Set Display Mode on upper left portion of the window to "HDMI Video."
- 3. Click on "Set."

2.5.5 Pattern Sequence

To display a sequence of patterns, follow these steps and refer to Figures 2-6 and 2-7:

- 1. Set Display Mode on upper left portion of the window to "Pattern Sequence" and click on "Set." The display will go dark.
- 2. Select "Pattern Sequence" tab on the lower half of the window.
- 3. Set Pattern settings by updating the following parameters inside the Pattern Setting box:
 - Bit Depth: bit depth of the image. Allowed values are from 1-8.
 - Number of Patterns: amount of patterns to display in sequence. Allowed values 1 to 96 divided by the bit depth. For example, if the bit depth is 8, the maximum amount of patterns is 96/8 = 12. If the bit depth is 1, the maximum amount of patterns is 96/1 = 96.
 - Include Inverted Patterns: display a pattern sequence with one pattern followed by its inverted pattern.



- Trigger Type: selects how the patterns are triggered.
 - Auto: patterns displayed after end of Trigger Period.
 - Command: patterns displayed when the Next button is pressed.
 - External (Positive): patterns displayed after an external active high trigger signal.
 - External (Negative):patterns display after an external active low trigger signal.
- LED Select: selects which color LED is active (Red, Green, or Blue).
- Trigger Delay: number of microseconds delay after trigger is received and pattern is displayed. See Figure 2-6.
- Exposure Time: number of microseconds the pattern is displayed. Input 0 to display the pattern through the whole trigger period. See Figure 2-6.
- Trigger Period: number of microseconds delay between two consecutive patterns are displayed. See Figure 2-6.



Figure 2-6. Trigger Period

- 4. Click on "Set" inside the Pattern Setting box.
- 5. Click on "..." to select the number of bitmap patterns matching the bit depth and number previously set.
- 6. Click on "Upload All." Wait for the command success and button to be deselected before proceeding.
- 7. Set Output Trigger Settings by updating the following parameters inside the Output Trigger Setting box.
 - Enable: enable output trigger on the Trigger Input/Output connector.
 - Delay: number of microseconds delay after pattern is displayed and trigger output is pulsed.
 - Pulse Width: width of trigger output pulse.
 - Invert: invert output trigger pulse from active high to active low pulse.
- 8. Click on "Set" inside the Output Trigger Setting box.
- 9. Click on "Start" to start the sequence. If Trigger Type "Command" is selected, then click "Next" to display the next pattern.

			Display M	ode			Image Setting
	Disconnect		Pattern	Sequence	~	Get	Long Axis Flip
lersion						Set	Short Axis Flip
SUI:	0.3.6		LED Curre	nt		1	Rotate -90 Degree
DM365:	2.3	Get Versions	Red	Green	Blue	Get	
PGA:	2.3.34		274	274	274	Set	Set Get
15P430:	2.3						
HDMI Video	Pattern Sequence	Test Pattern / Imag	e Solution ,	Upgrade	Camera		
	Start	Stop	lext		P	attern Image	
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Enable	Delay (us)	Pulse Width (us)	ſ	Cat			
T Terrard	0	0	7 2	GBL			
I I I I I I I I I I I I I I I I I I I				Set			

Figure 2-7. Pattern Sequence

Exposure Time is dependent on the bit-depth. See Section 3.3 for allowed exposure times.

WARNING

Changing the bit-depth, exposure, or pattern count requires that all the images need to be uploaded again. Uploading all the images is necessary since the pattern arrangement in the frame memory buffer is dependent on these settings.

2.6 Firmware Upgrades

Periodic upgrades to the firmware of the FPGA, DLPC300, MSP430, and EDID are accomplished through the DLP LightCrafter GUI. To upgrade the DM365 firmware, a micro-SD card with the new software is needed to load the NAND flash.

To upgrade the FPGA, DLPC300, MSP430, or EDID, perform the following steps:

- 1. Select the Solution/Upgrade Tab.
- 2. At the bottom of this tab, there is a "SW Package" section.
- 3. Select the appropriate device and then browse the file by clicking on "Browse"
 - To upgrade MSP430 firmware, select a TI-tagged file (*.txt).
 - To upgrade FPGA, select an "*.rbf" file.
 - To upgrade DLPC300 firmware, select a binary file (*.bin).
 - To upgrade EDID, select a binary file (*.bin).
- 4. Once the file is selected, click Install.

			Display Mod	de			Image Setting
	Disconnect		Pattern	Sequence	~	Get	Long Axis Flip
lersion GUI: DM365: FPGA: M5P430:	0.3.6 2.3 2.3.34 2.3	Get Versions	LED Curren Red 274	Green	Blue 274	Set Get Set	Short Axis Flip Rotate -90 Degree Set Get
HDMI Video	Pattern Sequence	Test Pattern / Imag	e Solution /	Upgrade	Camera		
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1-bit Patte	rn Red rn		Red Lu De	ave fresh Doad fault	MSP4: Y:/Lig	30 Software v	Browse 2011_12_26/frmsp430_full.bt

Figure 2-8. Firmware Upgrades

To upgrade the DM365 firmware, perform the following steps:

- 1. Insert and format micro-SD card with PC.
- 2. Run the "Windows Command Processor" as an administrator.
- 3. Change to the directory with the DM365 firmware (*.dat) and lcr_boot_sd.exe using the "cd" command.
- 4. In the "Windows Command Processor" run *lcr_boot_sd.exe* {*DM365 firmware file*} *E:* for a SD card mapped to the E: drive.
 - To create a bootable SD card, use the dm3xx_sdv*.dat firmware.



Solutions

- To create a SD card to flash the DLP LightCrafter NAND, use the dm3xx nandv*.dat firmware.
- 5. Insert micro-SD card with firmware into unpowered DLP LightCrafter.
- 6. Set the DIP switch on system board to the side closest to the micro-SD card connector
- 7. Power up the DLP LightCrafter and LED next to DM365 will light up red.
 - If booting from SD card instead of flashing the NAND, no further steps are needed.
- 8. Wait until LED next to DM365 lights up green. This should be a few seconds after the fourth splash screen.
- 9. Remove power from the DLP LightCrafter.
- 10. Remove micro-SD card from DLP LightCrafter and set DIP switch to the side closest to DM365.
- 11. Power the DLP LightCrafter, test screen of colored bars should appear after the splash screen if firmware has been successfully upgraded.

2.7 Solutions

Any of the parameters set on the GUI can be stored as a solution. This solution can later be recalled with a single button or set to run on Default. To create a solution, follow these steps and refer to Figure 2-8:

- 1. Set the appropriate settings such as LED Current, Pattern Sequence bit depth, number of patterns, input trigger, trigger period, exposure, time, display mode, etc.
- 2. Click on Solution/Upgrade tab.
- 3. Under Solutions box, enter a name and click "Save."
- 4. To manage stored solutions, use the following buttons:
 - Refresh: lists stored solutions
 - Load: load the currently selected solution
 - Default: sets the currently selected solution as the default solution when DLP® LightCrafter™ boots.
 - Delete: erases the currently selected solution

	Distance and the		Coport House		Cat	and a second
lersion	Disconnect		Pattern Sequence	~	Set	Long Axis Flip
5UI: DM365: IPGA: 1/SP430:	0.3.6 2.3 2.3.34 2.3	Get Versions	Red Green	Blue 274	Get Set	Rotate -90 Degree
HDMI Video	Pattern Sequence	Test Pattern / Image	Solution / Upgrade	Camera		
1-bit Patter	rn Red		Refresh	Y:/Ligh	ntCrafter/Releases/2	011_12_28)lcrmsp430_full.txt
			Default			

Figure 2-9. Solutions



Pattern Sequences

This chapter describes the pattern sequences supported by the DLP® LightCrafter™ Module

3.1 Pattern Sequence Background

The DLPC300 takes as input 16-, 18- or 24-bit RGB data at up to 60-Hz frame rate. This frame rate is composed of three colors (red, green, and blue) with each color equally divided in the 60-Hz frame rate. Thus, each color has a 5.55 ms time slot allocated. Because each color has 5-, 6-, or 8-bit depth, each color time slot is further divided into bit-planes. A bit-plane is just one-bit representation of all the pixels in the image. A 24-bit image is decomposed into its bit planes in Figure 3-1.





The length of each bit-plane in the time slot is weighted by the corresponding power of 2 of its binary representation. This provides a binary pulse-width modulation of the image. For example, a 24-bit RGB input has three colors with 8-bit depth each. Each color time slot is divided into eight bit-planes, with the sum of all bit planes in the time slot equal to 256. Figure 3-2 illustrates this partition of bits in a frame.







External Patterns

Therefore, a single video frame is composed of a series of bit planes. Because the DMD mirrors can be either on or off, an image is created by turning on the mirrors corresponding to the bit set in a bit plane. With the binary pulse-width modulation, the intensity level of the color is reproduced by controlling the amount of time the mirror is on. For a 24-bit RGB frame image inputted to the DLPC300, the DLPC300 creates 24 bit planes, stores them on the mDDR, and sends them to the DLP3000 DMD, one bit plane at a time. Depending on the bit weight of the bit plane, the DLPC300 controls the time this bit plane is exposed to light, controlling the intensity of the bit plane. To improve image quality in video frames, the bit planes, time slots, and color frames are intertwined and interleaved with spatial-temporal algorithms by the DLPC300.

For other applications where this image enhancement is not desired, the video processing algorithms can be bypassed and replaced with a specific set of bit planes. The bit depth of the pattern is then allocated into the corresponding time slots. Furthermore, an output trigger signal is also synchronized with these time slots to indicate when the image is displayed. For structured light applications this mechanism provides the capability to display a set of patterns and signal a camera to capture these patterns overlaid on an object.

3.2 External Patterns

Using the mechanism described in the previous section, an external device can feed patterns to the DLPC300 for display. Figure 3-3 illustrates the bit planes and corresponding output triggers for 3-bit, 6-bit, and 12-bit RGB.



Figure 3-3. Bit Planes and Triggers

While an external device is writing a frame to the DLPC300, the previous frame is displayed. Therefore, there is a lag of one video frame in relation to the output trigger signal.

Table 3-1 shows the allowed pattern combinations in relation to the bit depth of the external pattern.

COLOF	RMODE	NUMBER OF PATTERNS PER FRAME	FRAME RATE	PATTERN RATE
	1-bit per pixel	24		24 * Frame Rate
	2-bit per pixel	12		12 * Frame Rate
	3-bit per pixel	8		8 * Frame Rate
Manaahrama	4-bit per pixel	6		6 * Frame Rate
Wonochiome	5-bit per pixel	4	- - 15, 30, 45, _ or 60 Hz	4 * Frame Rate
	6-bit per pixel	4		4 * Frame Rate
	7-bit per pixel	3		3 * Frame Rate
	8-bit per pixel	2		2 * Frame Rate
	1-bit per color pixel (3-bit per pixel)	24		4 * Frame Rate
DCD	2-bit per color pixel (6-bit per pixel)	12		3 * Frame Rate
KGD	4-bit per color pixel (12-bit per pixel)	8		2 * Frame Rate
	8-bit per color pixel (24-bit per pixel)	1		Frame Rate

Table 3-1. Allowable External Pattern Combinations

3.3 Internal Patterns

In addition to the externally provided sequences through the 24-bit RGB interface of the DLPC300, DLP® LightCrafter[™] offers the ability to pre-load patterns into the DLPC300's memory (mDDR) to achieve faster frame rates. Once the patterns are pre-loaded, the FPGA manages the bit planes stored in the mDDR. The mDDR accommodates four 608 × 684 images of 24-bit RGB data or 96 bit planes (24 bit planes × 4 images). The 96 bit-plane buffer is arranged in a circular buffer style, meaning that the last bit plane addition to the buffer replaces the oldest stored bit plane.

The oldest set of bit planes in the bit-plane buffer is displayed. Thus, the displayed patterns will lag by 16.66 ms at 60 Hz frame rate while the circular buffer is filled. After the initial 16.66 ms delay, there is no additional delay for subsequent patterns since the circular buffer is filled.

With the FPGA, the pattern frame rate can be calculated with the following equation: Pattern Rate = (1/Pattern Exposure Period) + (Bit Plane Load Time) + (Buffer Rotate Overhead)

where

- Typical bit plane load time = 230 µs
- Typical buffer rotate overhead = 135 µs

Table 3-2 shows the maximum pattern rate that can be achieved by using a single FPGA's internal buffer in continuous mode.

cc	LOR MODE	MAXIMUM NUMBER OF PATTERNS	MAXIMUM PATTERN RATE
	1-bit per pixel	96	4000 Hz
	2-bit per pixel	48	1600 Hz
	3-bit per pixel	32	480 Hz
Manaahrama	4-bit per pixel	24	360 Hz
wonochrome	5-bit per pixel	16	240 Hz
	6-bit per pixel	16	240 Hz
	7-bit per pixel	12	180 Hz
	8-bit per pixel	12	120 Hz

Table 3-2. Maximum Internal Pattern Rate

(2)



Internal Patterns

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These locally stored patterns have a pre-defined exposure time that is detailed in Table 3-3. Note that the exposure time decrements by 500 μ s from the maximum exposure time. Thus, the minimum might not be a step size decrease from the second to last minimum exposure time.

BIT DEPTH	MAXIMUM EXPOSURE TIME (μs)	MINIMUM EXPOSURE TIME (μs)	STEP SIZE DECREASE (µs)
8-bit	20,000	8,333	500
7-bit	20,000	4,500	500
6-bit	20,000	2,500	500
5-bit	20,000	2,000	500
4-bit	20,000	1,600	500
3-bit	20,000	1,470	500
2-bit	20,000	666	500
1-bit	100,000	250	500

Table 3-3. Internal Pattern Exposure Time



Connectors

This chapter describes the connector pins of the DLP® LightCrafter™ Module.

4.1 Trigger Connector

The trigger connector pins are listed in Table 4-1. Two matching four pin mating connector part numbers are:

- Molex part number: 51021-0400
- Digi-Key part number: WM1722-ND

The corresponding crimps part numbers are:

- Molex part number: 50079-8000
- Digi-Key part number: WM1142CT-ND

Table 4-1. Trigger Connector Pins

DESCRIPTION	PIN	SUPPLY RANGE
Trigger Supply	1	3.3 V
Trigger Input	2	3.3 V
Trigger Output	3	3.3 V
Ground	4	3.3 V

4.2 Camera Connector

The camera connector pins are shown in Table 4-2. The supplies are configurable through resistor population options between 1.8 V, 2.8 V, and 3.3 V.

DESCRIPTION	PIN	SUPPLY RANGE
Camera Data[2]	1	2.8 V (CAM_IO)
Camera Data[3]	2	2.8 V (CAM_IO)
Camera Data[4]	3	2.8 V (CAM_IO)
Camera Data[5]	4	2.8 V (CAM_IO)
Camera Data[6]	5	2.8 V (CAM_IO)
Camera Data[7]	6	2.8 V (CAM_IO)
Camera Data[8]	7	2.8 V (CAM_IO)
Camera Data[9]	8	2.8 V (CAM_IO)
Camera PCLK	9	2.8 V (CAM_IO)
Digital Supply	10	1.8 V (CAM_DIGITAL)
I/O Supply	11	2.8 V (CAM_IO)
Ground	12	0 V
Analog Supply	13	2.8 V (CAM_ANALOG)
Camera VSYNC	14	2.8 V (CAM_IO)
Camera HSYNC	15	2.8 V (CAM_IO)
CLKIN 24 MHz	16	2.8 V (CAM_IO)

Table 4-2. Camera Connector Pins

DESCRIPTION	PIN	SUPPLY RANGE
Ground	17	0 V
I ² C SDA	18	2.8 V (CAM_IO)
I ² C SCL	19	2.8 V (CAM_IO)
Camera Reset	20	2.8 V (CAM_IO)
Camera StandBy	21	2.8 V (CAM_IO)
Camera SubAddr	22	2.8 V (CAM_IO)
Camera Data[0]	23	2.8 V (CAM_IO)
Camera Data[1]	24	2.8 V (CAM_IO)
No Connect	25	
Camera Trigger	26	2.8 V (CAM_IO)
Camera DataEn	27	2.8 V (CAM_IO)
No Connect	28	

Table 4-2. Camera Connector Pins (continued)

4.3 UART

The UART connector pins are shown in Table 4-3.

Table 4-3. UART Connector Pins

DESCRIPTION	PIN	SUPPLY RANGE
Ground	1	0 V
RX	2	3.3 V
TX	3	3.3 V

4.4 I²C

The I²C connector pins are shown in Table 4-4.Two matching four pin mating connector part numbers are:

- Molex part number: 51021-0400
- Digi-Key part number: WM1722-ND

The corresponding crimps part numbers are:

- Molex part number: 50079-8000
- Digi-Key part number: WM1142CT-ND

Table 4-4. I²C Connector Pins

DESCRIPTION	PIN	SUPPLY RANGE
I ² C SDA	1	3.3 V
I ² C SCL	2	3.3 V
Ground	3	0 V
3.3 V Supply	4	3.3 V

4.5 Fan

The fan connector pins are shown in Table 4-5. Two matching connector part numbers are:

- Molex part number: 51021-0200
- Digi-Key part number: WM1720-ND

The corresponding crimps part numbers are:

• Molex part number: 50079-8000



Digi-Key part number: WM1142CT-ND •

Table 4-5. Fan Connector Pins

DESCRIPTION	PIN	SUPPLY RANGE
Power	1	5 V (SYSPWR)
Switch to Ground	2	0 V

4.6 Power

The power connector pins are shown in Table 4-6. Two matching connector part numbers are:

- JST part number: PHR-2(P)
- Digi-Key part number: 455-1165-ND

The corresponding crimps part numbers are:

- JST part number: SPH-002T-P0.5L •
- Digi-Key part number: 455-2148-1-ND •

Table 4-6. Power Connector Pins

DESCRIPTION	PIN	SUPPLY RANGE
Input Supply	1	5 V (SYSPWR)
Ground	2	0 V



Revision A History

Revision A History

Cł	Changes from Original (January 2011) to A Revision	
•	Added warning about pattern reload when parameters are changed.	23

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Revision B History

Changes from A Revision (February 2013) to B Revision

-		
•	Added "Other items needed for operation" section	10
•	Added power connector specifications	11
•	Changed and clarified UART mini-plug connection description	11
•	Changed PC Software section to reflect changes to installation instructions	18
•	Changed warning about reload patterns when parameters are changed	23
•	Added steps to upgrade DM365 firmware	23

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Page

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Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

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This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC – INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

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Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

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- 2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
- 3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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- 2. You have full and exclusive responsibility to assure the safety and compliance of your products with all such laws and other applicable regulatory requirements, and also to assure the safety of any activities to be conducted by you and/or your employees, affiliates, contractors or designees, using the EVM. Further, you are responsible to assure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard.
- 3. Since the EVM is not a completed product, it may not meet all applicable regulatory and safety compliance standards (such as UL, CSA, VDE, CE, RoHS and WEEE) which may normally be associated with similar items. You assume full responsibility to determine and/or assure compliance with any such standards and related certifications as may be applicable. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
- 4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

Certain Instructions. It is important to operate this EVM within TI's recommended specifications and environmental considerations per the user guidelines. Exceeding the specified EVM ratings (including but not limited to input and output voltage, current, power, and environmental ranges) may cause property damage, personal injury or death. If there are questions concerning these ratings please contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, some circuit components may have case temperatures greater than 60°C as long as the input and output are maintained at a normal ambient operating temperature. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors which can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during normal operation, please be aware that these devices may be very warm to the touch. As with all electronic evaluation tools, only qualified personnel knowledgeable in electronic measurement and diagnostics normally found in development environments should use these EVMs.

Agreement to Defend, Indemnify and Hold Harmless. You agree to defend, indemnify and hold TI, its licensors and their representatives harmless from and against any and all claims, damages, losses, expenses, costs and liabilities (collectively, "Claims") arising out of or in connection with any use of the EVM that is not in accordance with the terms of the agreement. This obligation shall apply whether Claims arise under law of tort or contract or any other legal theory, and even if the EVM fails to perform as described or expected.

Safety-Critical or Life-Critical Applications. If you intend to evaluate the components for possible use in safety critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, such as devices which are classified as FDA Class III or similar classification, then you must specifically notify TI of such intent and enter into a separate Assurance and Indemnity Agreement.

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